

Report NO.: AE200921001

## **Testing and Innovation Center**

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# **Solderability Test report**

Futaijie technology development (Shenzhen) Co., Ltd
Testing and Innovation Center
No.2, 2nd Donghuan Road, 10th Yousong Industrial District,
Longhua, Shenzhen, Guangdong, China

Client:	ICKEY
Add. of Client:	Room402, Fuji-Xerox F building, Yinxing Technology park, NO. 1301
Add. of Client:	Guanguang Road, Guanlan Street, Longhua district, ShenZhen City
Manufacturer:	TI
Sample Type:	IC
Model / PN:	LM4041DIM3-1.2/NOPB
Sample Qty.:	5
Date Received:	2020/9/21
Date Tested:	2020/9/21

Approved by: Checked by:	by:	Checked by:	文学	3
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Prepared by Tank Zhang

Seal of testing center

Date Reported:





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## **Test Report**

#### 1. Test Result

	Test Item	Sample Qty.	Test Date	Test Result		
1	Solderability (wetting	5 pcs	2020/09/21		Fail	
'	balance)	o pes	2020/09/21		l'all	

Summary: No damage of the sample, no obvious abnormality.

Pass: The test results meet the standard / customer judgment requirements

Fail: The test results do not meet the standard / customer judgment requirements

N.A.: Not applicable

### 2. Sample Description

Item	Appearance				
Top View	RID				
<b>Bottom View</b>	0890				

## 3. Test Purpose

To judge the solderability of components.





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## 4. Test Equipment

Item	Equipment	Supplier	Model	Validity period of calibration
1	Wetting balance	XIMEI	MUSTIII	2021.4.21

## 5. Laboratory Ambience Condition

Temperature: 25±5°C

Relative humidity: (25~85) %RH

#### 6. Test Condition

1) Wetting Temperature: 245 °C ±5 °C

2) Wetting Time: 5±0.5 Seconds

3) Immersion and withdrawal speed: 1mm/s

4) Immersion depth: 0.1mm

5) Dipping angle: 90°

6) Flux: Rosin mildly activated flux(RMA, 0.2%CI)

7) Solder alloy: Ecosol TSC(Sn96.5Ag3.0Cu0.5)



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#### 7. Reference Document

The Solderability test method conforms to IEC 60068-2-69 2007, and the process shows as follows:

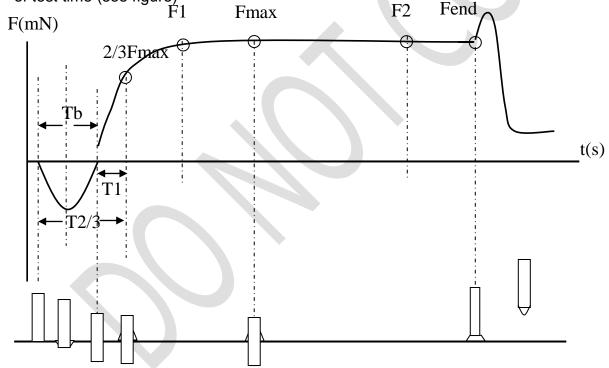
After applying the liquid flux to the specimen termination and mounting the specimen in a suitable holder, the specimen is suspended from a sensitive balance. The specimen termination is brought into contact with the cleaned surface of a solder bath and immersed to the prescribed depth. The resultant forces of buoyancy and surface tension acting upon the immersed termination are detected by a transducer and converted to a signal which is continuously monitored as a function of time, and displayed on a computer screen.

The wetting speed and the extent of wetting are derived from the force against time curve. Evaluation of resultant graph curves from testing of microelectronic leads.:

The criteria for acceptable solderability during the evaluation of the recordings are:

a. That the recorded signal trace crosses the zero balance point at or before 0.59 seconds of test time.

b. That the recorded signal trace reaches two-thirds of its maximum value in 1 second or less of test time (see figure)



Tb----Zero cross time

T2/3-----Time to 2/3Fmax

F1-----Wetting force at 2 s

Fmax-----Maximum wetting force

Sb-----Fend/Fmax

T1-----Wetting up time

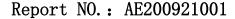
2/3Fmax----2/3 of Max force

F2-----Wetting force at 5 s

Fend-----End wetting force

Foxconn-QCF







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## 8. Criteria of Judgment

Tb < 0.60s; T2/3 < 1.0s;

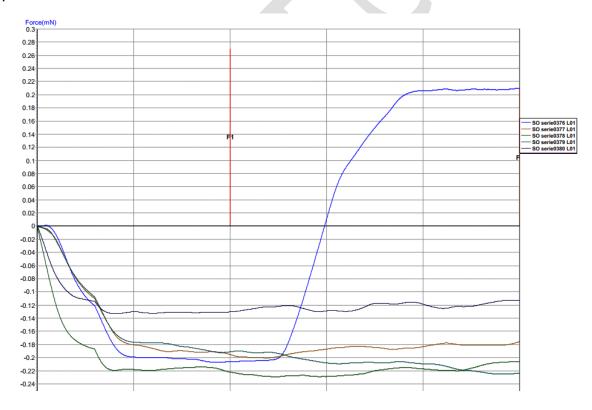
(Reference: F1  $\geq$ 0.21mN at 2 sec and F2  $\geq$  0.17mN at 5 sec.).

#### 9. Test Data

#### Sample 1-5

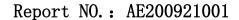
Sample	No.	Tb	Fmax	F1	F2	T2/3	Result
Samp	le 1	2.979	0.210	-0.206	0.210	3.444	Retarded wetting
Samp	le 2	0.000	-0.176	-0.195	-0.176	4.998	Non-wetting
Samp	le 3	0.000	-0.206	-0.222	-0.206	4.965	Non-wetting
Samp	le 4	0.000	-0.224	-0.191	-0.224	4.992	Non-wetting
Samp	le 5	0.000	-0.113	-0.130	-0.113	5.010	Non-wetting

#### Test profiles





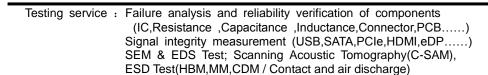






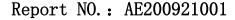
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# **Appendix** Slow wetting Non-wetting oor wetting Buoyant specimen Very fast wetting Good wetting Unstable wetting Fast wetting limited by thermal demand



Retarded wetting







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\*\*\*\*\*End\*\*\*\*\*

